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## Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

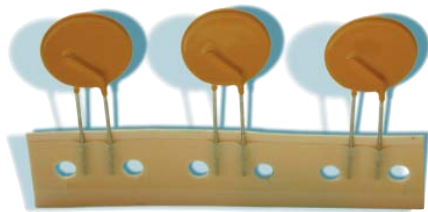
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



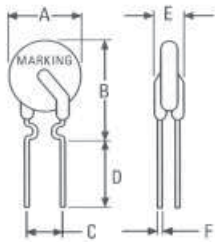
# RLD60

## Radial Leaded, 60 V

## Specifications



Dimensions (mm)



### Standard

UL 1434 1<sup>st</sup> Edition  
CSA C22.2 No. 0 CSA TIL No. CA-3A

### Approvals

cULus Recognition  
TÜV

### Features

These 60V RLDs were designed to be general-purpose resettable fuses. As such, they are capable of protecting a large variety of circuits, including power supplies, speakers, security and alarm systems, certain motors etc.

### Packaging

A\* bulk  
G tape and reel  
F\* tape and ammo  
\* preferred type

### Materials

Insulating Material: Yellow Epoxy Polymer, UL 94 V-0

Round Pins: Copper alloy, tin plated

### Max. Device Surface Temperature in Tripped State

125 °C

### Operating / Storage Temperature

-40 °C to +85 °C (consider derating)

### Humidity Ageing

+85 °C, 85 % R.H., 1000 hours, ± 5 % typical resistance change

### Soldering Characteristics

Solderability per MIL-STD-202, Method 208E

### Thermal Shock

MIL-STD-202F, Method 107G

+125 °C to -40 °C 10 times, ±10 % typical resistance change

### Solvent Resistance

MIL-STD-202, Method 215F, no change

### Marking

"P", voltage, amperage rating, lot number



Model	Dimensions (mm)					Physical Characteristics		packaging quantity	
	A Max	B Max	C typ	D Min	E Max	Lead	Material	bag	ammo
RLD60P010X	7.4	12.7	5.1	7.6	3.1	0.51 dia.	Sn/CuFe	500	2,000
RLD60P017X	7.4	12.7	5.1	7.6	3.1	0.51 dia.	Sn/CuFe	500	2,000
RLD60P020X	7.4	12.2	5.1	7.6	3.1	0.51 dia.	Sn/CuFe	500	2,000
RLD60P025X	7.4	12.7	5.1	7.6	3.1	0.51 dia.	Sn/CuFe	500	2,000
RLD60P030X	7.4	13.0	5.1	7.6	3.1	0.51 dia.	Sn/CuFe	500	2,000
RLD60P040X	7.6	13.5	5.1	7.6	3.1	0.51 dia.	Sn/CuFe	500	2,000
RLD60P050X	7.9	13.7	5.1	7.6	3.1	0.51 dia.	Sn/Cu	500	2,000
RLD60P065X	9.7	14.5	5.1	7.6	3.1	0.51 dia.	Sn/Cu	500	2,000
RLD60P075X	10.4	15.2	5.1	7.6	3.1	0.51 dia.	Sn/Cu	500	2,000
RLD60P090X	11.7	15.7	5.1	7.6	3.1	0.51 dia.	Sn/Cu	500	2,000
RLD60P110X	13.0	18.0	5.1	7.6	3.1	0.81 dia.	Sn/Cu	500	1,000
RLD60P135X	14.5	19.6	5.1	7.6	3.1	0.81 dia.	Sn/Cu	100	1,000
RLD60P160X	16.3	21.3	5.1	7.6	3.1	0.81 dia.	Sn/Cu	100	1,000
RLD60P185X	17.8	22.9	5.1	7.6	3.1	0.81 dia.	Sn/Cu	100	1,000
RLD60P250X	21.3	26.4	10.2	7.6	3.1	0.81 dia.	Sn/Cu	100	1,000
RLD60P300X	24.9	30.0	10.2	7.6	3.1	0.81 dia.	Sn/Cu	100	1,000
RLD60P375X	28.4	33.5	10.2	7.6	3.1	0.81 dia.	Sn/Cu	100	800

Permissible continuous operating current is ≤ 100 % at ambient temperature of 20 °C (68 °F).

Model	I <sub>hold</sub> (A)	I <sub>Trip</sub> (A)	V <sub>max. dc</sub> (V)	I <sub>max.</sub> (A)	max. time to trip (s @ A)	P <sub>d max.</sub> (W)	Resistance		Approvals	
							R <sub>min.</sub> (Ω)	R <sub>1max.</sub> (Ω)	UL	CSA
RLD60P010X	0.10	0.20	60	40	4.00 @ 0.50	0.38	2.500	7.500	•	p
RLD60P017X	0.17	0.34	60	40	3.00 @ 0.85	0.48	3.300	8.000	•	p
RLD60P020X	0.20	0.40	60	40	2.20 @ 1.00	0.41	1.830	4.400	•	•
RLD60P025X	0.25	0.50	60	40	2.50 @ 1.25	0.45	1.250	3.000	•	•
RLD60P030X	0.30	0.60	60	40	3.00 @ 1.50	0.49	0.880	2.100	•	•
RLD60P040X	0.40	0.80	60	40	3.80 @ 2.00	0.56	0.550	1.290	•	•
RLD60P050X	0.50	1.00	60	40	4.00 @ 2.50	0.77	0.500	1.170	•	•
RLD60P065X	0.65	1.30	60	40	5.30 @ 3.25	0.88	0.310	0.720	•	•
RLD60P075X	0.75	1.50	60	40	6.30 @ 3.75	0.92	0.250	0.600	•	•
RLD60P090X	0.90	1.80	60	40	7.20 @ 4.50	0.99	0.200	0.470	•	•
RLD60P110X	1.10	2.20	60	40	8.20 @ 5.50	1.50	0.150	0.380	•	•
RLD60P135X	1.35	2.70	60	40	9.60 @ 6.75	1.70	0.120	0.300	•	•
RLD60P160X	1.60	3.20	60	40	11.40 @ 8.00	1.90	0.090	0.220	•	•
RLD60P185X	1.85	3.70	60	40	12.60 @ 9.25	2.10	0.080	0.190	•	•
RLD60P250X	2.50	5.00	60	40	15.60 @ 12.50	2.50	0.050	0.130	•	•
RLD60P300X	3.00	6.00	60	40	19.80 @ 15.00	2.80	0.040	0.100	•	•
RLD60P375X	3.75	7.50	60	40	24.00 @ 18.75	3.20	0.030	0.080	•	•

NOTE:

I<sub>hold</sub> = Hold current: maximum current device will pass without tripping in 20 °C still air.  
I<sub>Trip</sub> = Trip current: minimum current at which the device will trip in 20 °C still air.  
V<sub>max.</sub> = Maximum voltage device can withstand without damage at rated current (I<sub>max.</sub>)  
I<sub>max.</sub> = Maximum fault current device can withstand without damage at rated voltage (V<sub>max.</sub>)

P<sub>d</sub> = Power dissipated from device when in the tripped state at 20 °C still air.  
R<sub>min.</sub> = Minimum resistance of device in initial (un-soldered) state.  
R<sub>1max.</sub> = Maximum resistance of device at 20 °C measured one hour after tripping for 20 s.  
**Caution: Operation beyond the specified rating may result in damage and possible arcing and flame. Specifications are subject to change without notice**

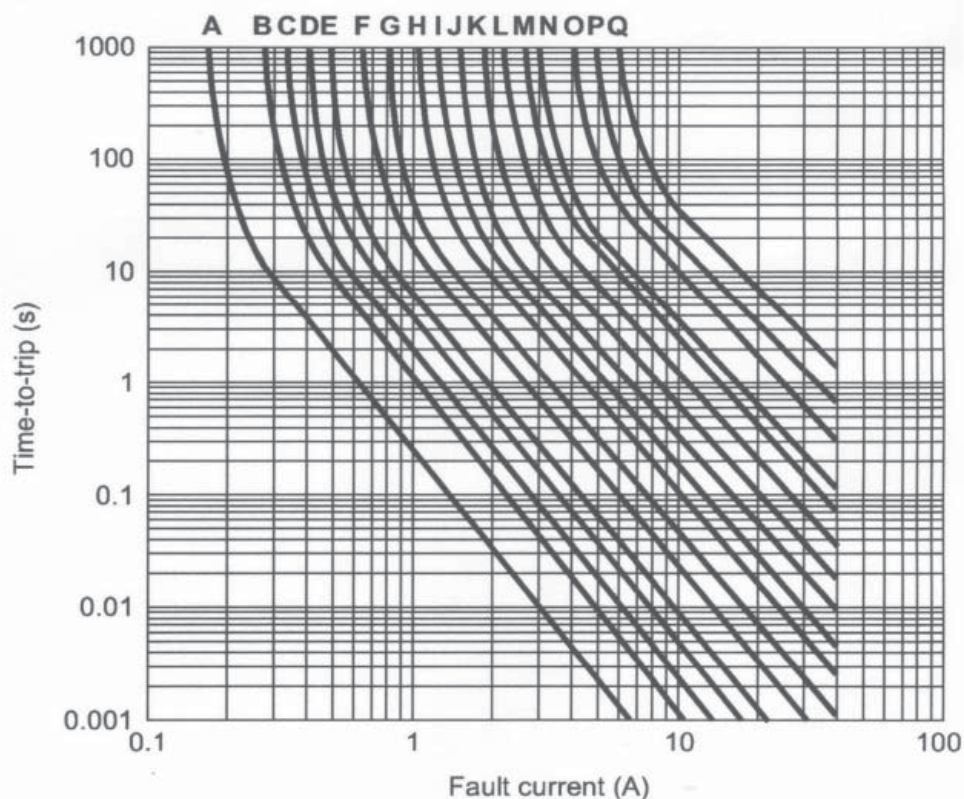
Order Information

Qty.	Order-Number	Model	* Packaging
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\* optional "F" for lead free devices



# RLD60



- A: RLD60P010X
- B: RLD60P017X
- C: RLD60P020X
- D: RLD60P025X
- E: RLD60P030X
- F: RLD60P040X
- G: RLD60P050X
- H: RLD60P065X
- I: RLD60P075X
- J: RLD60P090X
- K: RLD60P110X
- L: RLD60P135X
- M: RLD60P160X
- N: RLD60P185X
- O: RLD60P250X
- P: RLD60P300X
- Q: RLD60P375X

## Thermal Derating Chart

Model	Ambient Operation Temperature - $I_{hold}$ (A)								
	-40 °C	-20 °C	0 °C	23 °C	40 °C	50 °C	60 °C	70 °C	85 °C
RLD60P010X	0.16	0.14	0.12	0.10	0.08	0.07	0.06	0.05	0.04
RLD60P017X	0.26	0.23	0.20	0.17	0.14	0.12	0.11	0.09	0.07
RLD60P020X	0.31	0.27	0.24	0.20	0.16	0.14	0.13	0.11	0.08
RLD60P025X	0.39	0.34	0.30	0.25	0.20	0.18	0.16	0.14	0.10
RLD60P030X	0.47	0.41	0.36	0.30	0.24	0.22	0.19	0.16	0.12
RLD60P040X	0.62	0.54	0.48	0.40	0.32	0.29	0.25	0.22	0.16
RLD60P050X	0.78	0.68	0.60	0.50	0.41	0.36	0.32	0.27	0.20
RLD60P065X	1.01	0.88	0.77	0.65	0.53	0.47	0.41	0.35	0.26
RLD60P075X	1.16	1.02	0.89	0.75	0.61	0.54	0.47	0.41	0.30
RLD60P090X	1.40	1.22	1.07	0.90	0.73	0.65	0.57	0.49	0.36
RLD60P110X	1.71	1.50	1.31	1.10	0.89	0.79	0.69	0.59	0.44
RLD60P135X	2.09	1.84	1.61	1.35	1.09	0.97	0.85	0.73	0.54
RLD60P160X	2.48	2.18	1.90	1.60	1.30	1.15	1.01	0.86	0.64
RLD60P185X	2.87	2.52	2.20	1.85	1.50	1.33	1.17	1.00	0.74
RLD60P250X	3.88	3.40	2.98	2.50	2.03	1.80	1.58	1.35	1.00
RLD60P300X	4.65	4.08	3.57	3.00	2.43	2.16	1.89	1.62	1.20
RLD60P375X	5.81	5.10	4.46	3.75	3.04	2.70	2.36	2.03	1.50